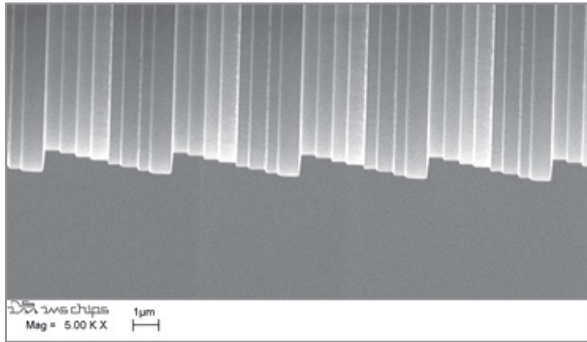
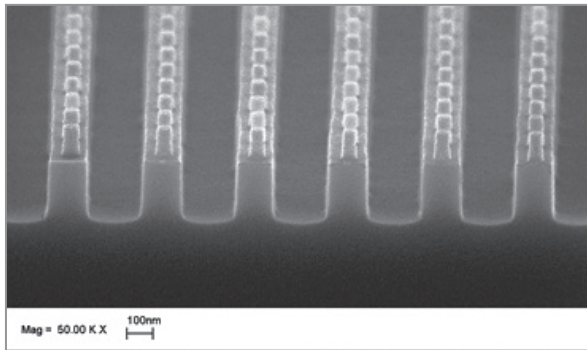


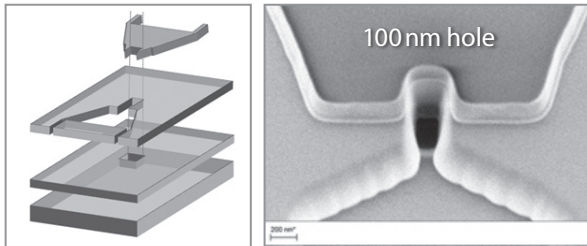
## Multi-layer 3D



3 layer exposures ► 8 steps, 5 µm pitch

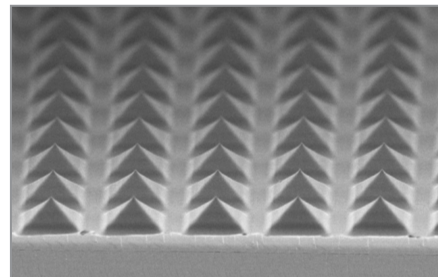
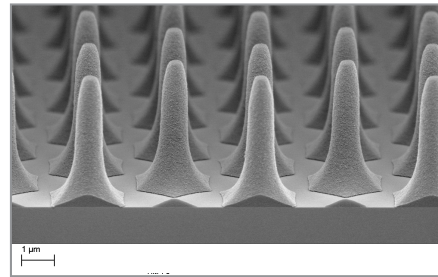
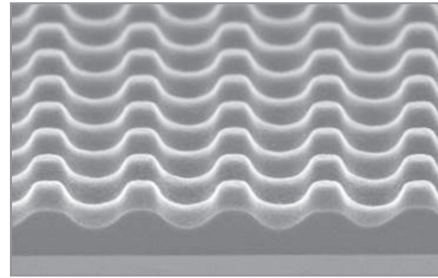


60 nm pillars on 120 nm lines

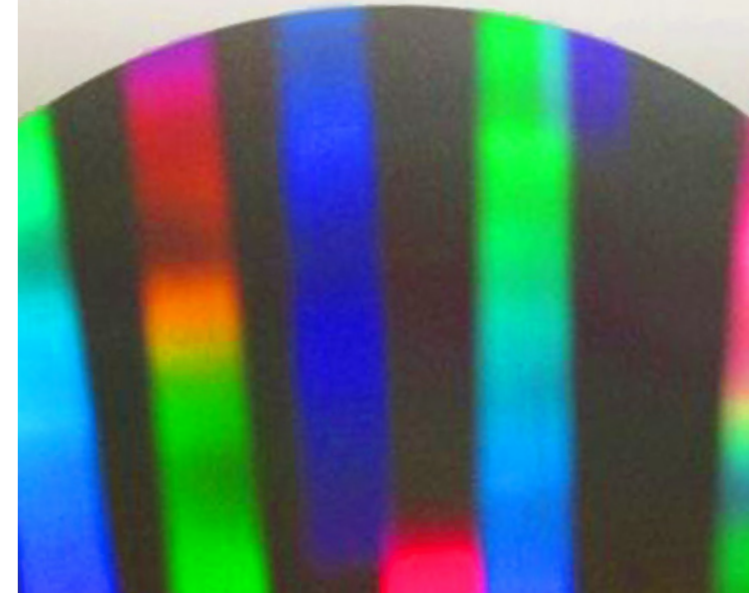


Master for HP self alignment technology

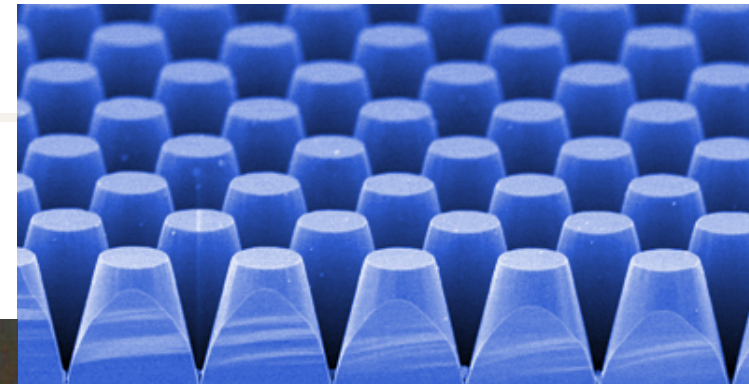
## Analog 3D



# MASTER STAMPS



  
INSTITUT FÜR MIKROELEKTRONIK STUTTGART



  
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# MASTER STAMPS

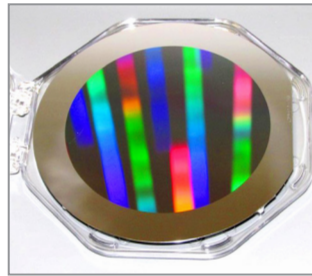
## Substrates

## Binary

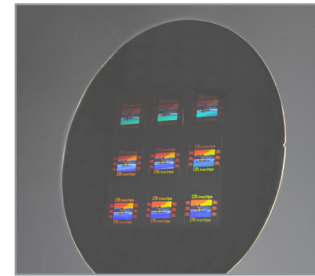
We provide master stamps for any replication techniques and for versatile applications

- Material: silicon, quartz, resist
- Stamp size: from a few mm<sup>2</sup> up to substrate size
- Feature types: binary, multi-level 3D, analog 3D
- Wide range of pattern dimensions from nano-meter- to micrometer-scale
- Optionally, pattern generation on pedestal
- Detailed characterization by in-line measurement tools
- Fabrication in a certified line in an ISO4 clean room

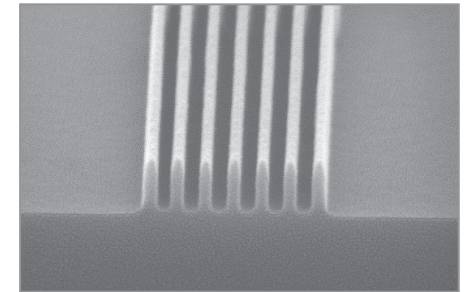
Based on our experience we assist with our customers to identify the most appropriate solution for them.



6", 8" Si wafer

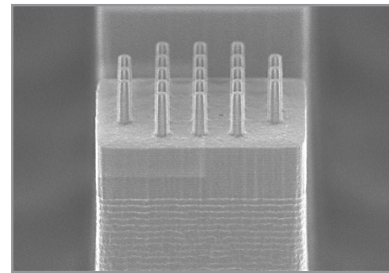


6", 8", 12" Qz wafer

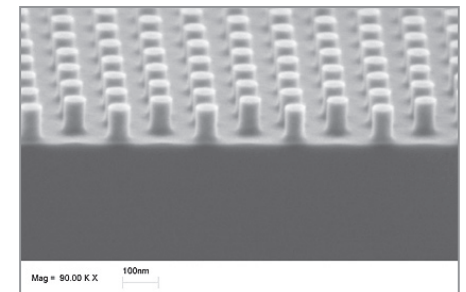


40 nm half pitch

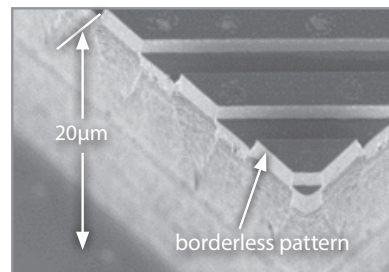
## Patterning on Pedestal



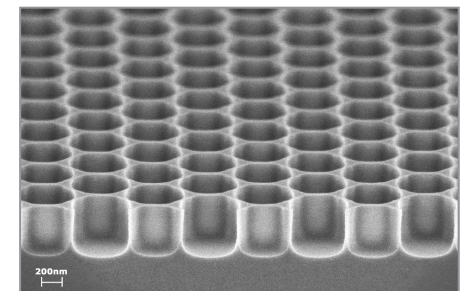
500nm pillars on a 15µm high pedestal



50 nm half pitch



borderless patterning on a pedestal



500 nm diameter

